## AMENDMENTS TO THE CLAIMS

Docket No.: 20154/0204315-US0

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims:**

Claim 1 (currently amended): A method of producing a composite soft magnetic material having high strength and high specific resistance, the method comprising the steps of:

heating at a temperature of 60 to 110 °C -mixture powder comprising having a composition containing

0.05 to [[-]]1 wt% of polyimide resin powder having an average particle diameter of 1 to 100  $\mu m$ ,

0.002 to [[-]]1 wt% of fine amide-based wax powder having an average particle diameter of 1 to 20  $\mu m$ , and

the balance composed of insulating film-coated soft magnetic powder obtained by forming an insulating film on the surface of soft magnetic powder, at a temperature of 60 to 110 °C;

filling the heated mixture powder in a mold which is heated at a temperature of 100 to 150 °C:

compression-molding the heated mixture powder at a molding pressure of 700 to 1200 MPa to obtain a compact; and

curing the obtained compact at a temperature of 225 to 300 °C.

Claim 2 (currently amended): The method of producing the composite soft magnetic material according to Claimclaim 1, wherein the insulating film-coated soft magnetic powder is phosphate film-coated iron powder obtained by forming a phosphate film on the surface of pure iron powder.

Claim 3 (currently amended): A composite soft magnetic <u>material powder</u> having high strength and high specific resistance, which is produced by the method of claim <u>laccording to Claim 1 or 2</u>.

Claim 4 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 2.

Claim 5 (new): The method of claim 1, wherein the polyimide resin powder comprises wholly aromatic polyimide resin powder or bismaleide-based polyimide resin powder or both.

Claim 6 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 5.

Claim 7 (new): The method of claim 1, wherein the average particle diameter of the polyimide resin powder is 10 to 80  $\mu m$ .

Claim 8 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 7.

Claim 9 (new): The method of claim 1, wherein the average particle diameter of the polyimide resin powder is 10 to 50  $\mu m$ .

Claim 10 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 9.

Claim 11 (new): The method of claim 1, wherein the amount of the polyimide resin powder in the mixture powder is 0.1 to 0.5 wt%.

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Claim 12 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 11.

Claim 13 (new): The method of claim 1, wherein the amount of the fine amide-based wax powder in the mixture powder is 0.004 to 0.05 wt%.

Claim 14 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 13.

Claim 15 (new): The method of claim 1, wherein the average particle diameter of the fine amide-based wax powder is 1 to  $10 \mu m$ .

Claim 16 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 15.

Claim 17 (new): The method of claim 1, wherein the fine amide-based wax powder is ethylenebisstearoamide, ethylenebislauramide, or methylenebisstearoid, or a mixture thereof.

Claim 18 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 17.

Claim 19 (new): The method of claim 1, wherein the compact is cured for 30 to 60 minutes.

Claim 20 (new): A composite soft magnetic material having high strength and high specific resistance, produced by the method of claim 19.